FOX-NP™
FULL WAFER CONTACT

Full Wafer & Singulated Die / Module Test System

Compact High Power Test and Reliability Verification Solution for Logic/Memory/Photonic Devices

System Benefits

- **Compact Flexible Solution for High Throughput Reliability Verification and Test**
  - Handles full wafer / panel / singulated die / module applications
  - Identifies failing logic/memory/photonic die before final package integration
  - High power thermal chuck dual Blade (slot) capability using WaferPak™ contactors or DiePak® carriers (for singulated die/modules)
- **Cost-Effective Solution for High Power Wafer/Die/Module Verification and Test**
  - Configurable channel resources per Blade (slot): Universal Channel Modules, High Voltage Channel Modules or High Current Channel Modules
  - Up to 2,048 "Universal Channel" resources: (I/O / Clock / PPMU / DPS) per Blade with deep scan, pattern data and capture memory per channel for test of devices with BIST/DFT
  - Up to 1,024 high voltage (29 V) or high current (2 A) sources resources per Blade
- **Production Proven Full-Wafer Reliability Verification & Test Solution**
  - Reduces test costs by functionally testing wafers/die/modules during reliability verification
  - Offers a total solution when configured with a WaferPak contactor / DiePak carrier and Wafer Aligner / DiePak Loader
  - Protects devices with individual per channel over-current and over-voltage protection

"Setting the Test Standard for Tomorrow"

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AEHR TEST SYSTEMS